DECLARATION FOR UTILITY OR DESIGN PATENT APPLICATION		Attorney Docket No.	: DOCKET 65611 (P 6653)
		First Named Inventor	r: Rajagopalan, et al.
[X]Declaration Submitted With Initial Filing	[]Declaration ) Submitted ) After ) Initial ) Filing	Application Number:	TBD
		Filing Date:	Herewith
		Group Art Unit:	
,		Examiner Name:	

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

METHOD AND APPARATUS FOR THERMAL PROFILING OF FLIP-CHIP PACKAGES

the specification of which:

- [x] is attached hereto, or
- [] was filed by an authorized person on my behalf on
  as United States Application Number

  (Date)
  or PCT International Application Number
  and was amended on

  (Date)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119(a)-(d) or §365(b) of any foreign application(s) for patent or inventor's certificate, or §365(a) of any PCT international application which designated at least one country other than the United States of America, listed below, and I have also identified below, by checking the box, any foreign application for patent or inventor's certificate, or any PCT international application, on this invention filed by me or my legal representatives or assigns and having a filing date before that of the application on which priority is claimed:

Prior Foreign Certified
Application Foreign Priority Copy Attached
Number(s) Country Filing Date Not Claimed Yes No

N/A

I hereby claim the benefit under Title 35, United States Code, §119(e) of any United States provisional application(s) listed below:

Provisional Application Provisional Application
Number(s) Filing Date

N/A

I hereby claim the benefit under Title 35, United States Code, §120, of any prior United States application(s), or under §365(c) of any PCT international application(s) designating the United States of America, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT international application(s) in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose all information known by me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56, which became available between the filing date of the prior application(s) and the national or PCT international filing date of this application:

Filing Date of
Prior PCT U.S. or PCT
Prior U.S. International International Patent Number
Application Number Application (if applicable)

N/A

As a named inventor, I hereby appoint the following registered practitioners, with full power of substitution and revocation, to prosecute this application and to transact all business in the United States Patent and Trademark Office connected therewith, and request that all correspondence and telephone calls in respect to this application be directed to:

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<u>Registered</u> <u>Practitioner</u>	Reg.No.	<u>Registered</u> <u>Practitioner</u>	Reg.No.
Morgan L. Fitch, Jr. Francis A. Even Julius Tabin John F. Flannery Robert B. Jones James J. Schumann James J. Hamill Timothy E. Levstik Joseph E. Shipley Robert J. Fox Kenneth H. Samples Philip T. Petti	17,023 16,880 16,754 19,759 20,135 20,856 19,958 30,192 31,137 27,635 25,747 31,651	John Paniaguas Richard A. Kaba Karl R. Fink Thomas F. Lebens Donald A. Peterson Bruce R. Mansfield Scott J. Menghini Francis T. Kalinski David G. Pursel Ralph R. Veseli Bruce R. Hopenfeld Sandeep Jaggi	31,051 30,562 34,161 38,221 18,647 29,086 42,880 44,177 28,659 33,807 39,714 43,331

I hereby declare that all statements made herein of my own knowledge are true, and that all statements made herein on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity or enforceability of the application or any patent issued thereon.

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